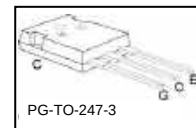
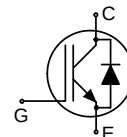


Low Loss DuoPack : IGBT in 2nd generation TRENCHSTOP™
with soft, fast recovery anti-parallel Emitter Controlled Diode

- Best in class TO247
- Short circuit withstand time – 10μs
- Designed for :
 - Frequency Converters
 - Uninterrupted Power Supply
- TRENCHSTOP™ 2nd generation for 1200 V applications offers :
 - very tight parameter distribution
 - high ruggedness, temperature stable behavior
- Easy paralleling capability due to positive temperature coefficient in $V_{CE(sat)}$
- Low EMI
- Low Gate Charge
- Very soft, fast recovery anti-parallel Emitter Controlled HE Diode
- Qualified according to JEDEC¹ for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>



Type	V_{CE}	I_C	$V_{CE(sat)}, T_j=25^\circ\text{C}$	$T_{j,max}$	Marking Code	Package
IKW40N120T2	1200V	40A	1.75V	175°C	K40T1202	PG-TO-247-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current ($T_j=150^\circ\text{C}$)	I_C	75 ²	A
$T_C = 25^\circ\text{C}$		40	
$T_C = 110^\circ\text{C}$			
Pulsed collector current, t_p limited by $T_{j,max}$	$I_{C,puls}$	160	
Turn off safe operating area	-	160	
$V_{CE} \leq 1200\text{V}, T_j \leq 175^\circ\text{C}$			
DC Diode forward current ($T_j=150^\circ\text{C}$)	I_F	75 ²	
$T_C = 25^\circ\text{C}$		40	
$T_C = 110^\circ\text{C}$			
Diode pulsed current, t_p limited by $T_{j,max}$	$I_{F,puls}$	160	
Gate-emitter voltage	V_{GE}	± 20	V
Short circuit withstand time ³⁾	t_{SC}	10	μs
$V_{GE} = 15\text{V}, V_{CC} \leq 600\text{V}, T_{j,start} \leq 175^\circ\text{C}$			
Power dissipation	P_{tot}	480	W
$T_C = 25^\circ\text{C}$			
Operating junction temperature	T_j	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	
Wavesoldering only, temperature on leads only			

¹ J-STD-020 and JESD-022

² Limited by bond wire

³⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.31	K/W
Diode thermal resistance, junction – case	R_{thJCD}		0.53	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=40A$				
		$T_j=25^{\circ}C$	-	1.75	2.2	
		$T_j=150^{\circ}C$	-	2.25	-	
		$T_j=175^{\circ}C$	-	2.3	-	
Diode forward voltage	V_F	$V_{GE}=0V, I_F=40A$				
		$T_j=25^{\circ}C$	-	1.75	2.2	
		$T_j=150^{\circ}C$	-	1.80	-	
		$T_j=175^{\circ}C$	-	1.80	-	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=1.5mA, V_{CE}=V_{GE}$	5.2	5.8	6.4	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$				mA
		$T_j=25^{\circ}C$	-	-	0.4	
		$T_j=150^{\circ}C$	-	-	4.0	
		$T_j=175^{\circ}C$	-	-	20	
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	-	-	200	nA
Transconductance	g_{fs}	$V_{CE}=20V, I_C=40A$	-	21	-	S